

IN THE SPECIFICATION

Please amend paragraph [0048] of the specification as follows:

[0048] In the SP method, the solderable areas 101 can be formed by one of two variations. In the first variation of the SP method, and as shown in Figures 5 and 7 ~~Figure 6~~, the solderable areas 101 are formed by first forming a metal coating 111 on the die attach region 21 of the leadframe 100. This metal coating is formed to substantially cover the entire portion of the leadframe that will contain the bump structures 36. The metal coating can be made of any metal or metal alloy that can be oxidized, such as Cu, Ag or Ni. The metal coating can be formed by any method known in the art, such as electroplating, electroless plating or sputtering. In one aspect of the invention, such as when Ni is used, the thickness of the metal coating can range from about 20 to about 80 microinches ~~microinches~~.